SWK4614B

40V Complementary Enhancement-Mode MOSFET

General Description

• Low gate charge.

- Use as a load switch.
- Use in PWM applications

Product Summary

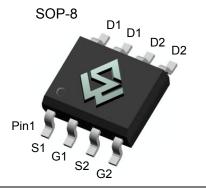
N-Channel

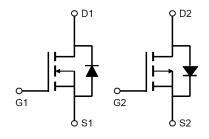
• BV_{DSS} = 40V

- R_{DS(on)} (@VGS= 10V) < 35mΩ
- $R_{DS(on)}$ (@VGS= 4.5V) < 50m Ω

P-Channel

- BV_{DSS} = -40V
- $R_{DS(on)}$ (@VGS= -10V) < $50m\Omega$
- $R_{DS(on)}$ (@VGS= -4.5V) < 75m Ω





N-Channel

P-Channel

Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

| Doromotor | Symbol | Maximum | | l luita |
|---|-----------------------------------|------------|------------|---------|
| Parameter | Symbol | N-Channel | P-Channel | Units |
| Drain-Source Voltage | V _{DS} | 40 | -40 | ٧ |
| Gate-Source Voltage | V _{GS} | ±20 | ±20 | ٧ |
| Drain Current (T _c =25°C) | | 7.0 | -7.5 | Α |
| Drain Current (T _c =75°C) | l _D | 5.6 | -5.1 | Α |
| Pulsed Drain Current ^a | I _{DM} | 14.5 | -13 | Α |
| Power Dissipation ^b (T _C =25°C) | P _D | 2.5 | 3.0 | W |
| Junction and Storage Temperature Range | T _J , T _{STG} | -55 ~ +150 | -55 ~ +150 | °C |

Thermal Characteristics

| Parameter | Symbol | Maximum | | Units | |
|--|------------------|-----------|-----------|-------|--|
| Faranietei | Symbol | N-Channel | P-Channel | Units | |
| Junction-to-Ambient ^a (t ≤ 10s) | | 50 | 60 | °C/W | |
| Junction-to-Ambient a,d (Steady-State) | $R_{\theta JA}$ | 80 | 90 | °C/W | |
| Junction-to-Case | R _{θJc} | 50 | 60 | °C/W | |



SWK4614B

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|---------------------|---------------------------------------|--|-----|------|------|-------|
| Off Char | acteristics | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} = 0V , I _D = 250uA | 40 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 40V , V _{GS} = 0V | | | 1 | uA |
| I_{GSS} | Gate-Body Leakage Current | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ±100 | nA |
| On Char | acteristics | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}$, $I_D = 250uA$ | 1 | | 2.5 | V |
| _ | Drain-Source On-State Resistance | V _{GS} = 10V , I _D = 5A | | 28 | 35 | mΩ |
| $R_{DS(ON))}$ | | V _{GS} = 4.5V , I _D = 4A | | 38 | 50 | mΩ |
| g FS | Forward Transconductance | V _{DS} = 5.0V , I _D = 12A | | 14 | | S |
| Drain-So | ource Diode Characteristics | | · | | | |
| V_{SD} | Diode Forward Voltage | V _{GS} = 0V , I _S = 1.0A | | | 1.2 | V |
| Is | Maximum Body-Diode Continuous Current | | | | 7.2 | Α |
| Dynamic | Characteristics | | | | | |
| C _{iss} | Input Capacitance | V _{DS} = 25V , V _{GS} = 0V f = 1.0MHz | | 493 | | pF |
| Coss | Output Capacitance | | | 56 | | pF |
| C_{rss} | Reverse Transfer Capacitance | 1.00012 | | 36 | | pF |
| Switchin | g Characteristics | | · | | | |
| Qg | Total Gate Charge | $V_{DS} = 20V$, $I_{D} = 3A$ $V_{GS} = 10V$ | | 10.5 | | nC |
| Q _{gs} | Gate-Source Charge | | | 2.25 | | nC |
| Q_{gd} | Gate-Drain Charge | VGS = 10 V | | 2.5 | | nC |
| t _{D(ON}) | Turn-On Delay Time | | | 9.9 | | ns |
| t _r | Turn-On Rise Time | $V_{DD} = 20V$, $ID = 4A$ | | 7.2 | | ns |
| t _{D(OFF)} | Turn-Off Delay Time | V_{GS} = 10 V R_{GEN} = 3.3 ohm | | 31 | | ns |
| t _f | Turn-Off Fall Time | | | 11 | | ns |

a. Repetitive rating, Pulse width limited by junction temperature T_{J(MAX)}=150 °C. Ratings are based on low frequency and duty cycles to keep initial T_I=25 °C

b. The power dissipation P_D is based on $T_{J(MAX)}$ =150 $^{\circ}C$, using \leq 10s junction-to-ambient thermal resistance.

c. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C. The value in any given application depends on the user's specific board design.

d. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.



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| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|----------------------|---------------------------------------|---|-----|------|------|-------|
| Off Char | acteristics | | · | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0V$, $I_D = -250uA$ | -40 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = -40V , V _{GS} = 0V | | | -1 | uA |
| I_{GSS} | Gate-Body Leakage Current | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ±100 | nA |
| On Char | acteristics | | | | | |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}$, $I_D = -250$ uA | -1 | | -2.5 | V |
| _ | Drain-Source On-State Resistance | $V_{GS} = -10V$, $I_D = -4.5A$ | | 40 | 50 | mΩ |
| R _{DS(ON))} | | $V_{GS} = -4.5V$, $I_D = -3.5A$ | | 60 | 75 | mΩ |
| g FS | Forward Transconductance | $V_{DS} = -5.0V$, $I_{D} = -6.0A$ | | 12 | | S |
| Drain-So | ource Diode Characteristics | | | | | |
| V_{SD} | Diode Forward Voltage | V _{GS} = 0V , I _S = -1.0A | | | -1.2 | V |
| Is | Maximum Body-Diode Continuous Current | | | | -7.5 | Α |
| Dynamic | Characteristics | | | | | |
| C _{iss} | Input Capacitance | | | 904 | | pF |
| C _{oss} | Output Capacitance | $V_{DS} = -15V$, $V_{GS} = 0V$ f = 1.0MHz | | 88 | | pF |
| C_{rss} | Reverse Transfer Capacitance | 1.00012 | | 70 | | pF |
| Switchin | g Characteristics | | · | | | |
| Qg | Total Gate Charge | $V_{DS} = -20V$, $I_{D} = -6A$ $V_{GS} = -4.5V$ | | 13 | | nC |
| Q _{gs} | Gate-Source Charge | | | 3.54 | | nC |
| Q_{gd} | Gate-Drain Charge | VGS 1.5V | | 3.1 | | nC |
| t _{D(ON}) | Turn-On Delay Time | | | 7.2 | | ns |
| t _r | Turn-On Rise Time | $V_{DD} = -20V$, $ID = -1A$ | | 5.8 | | ns |
| $t_{D(OFF)}$ | Turn-Off Delay Time | $V_{GS} = -10 \text{ V}$ $R_{GEN} = 3.3 \text{ ohm}$ | | 18.6 | | ns |
| t _f | Turn-Off Fall Time | | | 6.6 | | ns |

a. Repetitive rating, Pulse width limited by junction temperature T_{J(MAX)}=150 °C. Ratings are based on low frequency and duty cycles to keep initial T₁=25 °C

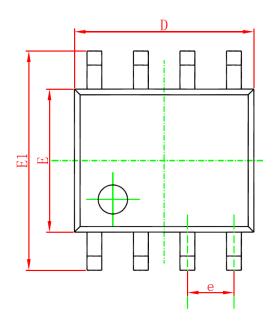
b. The power dissipation P_D is based on $T_{J(MAX)}$ =150 $^{\circ}C$, using \leqslant 10s junction-to-ambient thermal resistance.

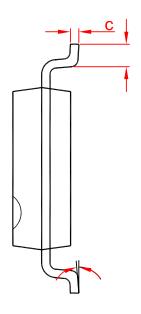
c. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C. The value in any given application depends on the user's specific board design.

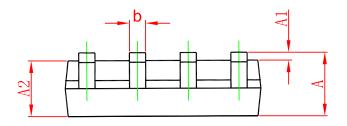
d. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.



SOP-8 Package Outline







| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|------------|---------------------------|-------|----------------------|-------|
| Symbol | Min. | Max. | Min. | Max. |
| Α | 1.350 | 1.750 | 0.053 | 0.069 |
| A 1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| С | 0.170 | 0.250 | 0.006 | 0.010 |
| D | 4.700 | 5.100 | 0.185 | 0.200 |
| E | 3.800 | 4.000 | 0.150 | 0.157 |
| E1 | 5.800 | 6.200 | 0.228 | 0.244 |
| е | 1.270(BSC) | | 0.050(BSC) | |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| θ | 0° | 8° | 0° | 8° |

单击下面可查看定价,库存,交付和生命周期等信息

>>SiliconWisdom(矽睿半导体)